

ABSTRACT

A bonding device. A flexible platen is disposed between an upper platen assembly (9) and a transmission device, and the flexible platen of the upper platen assembly (9) is located inside a vacuum chamber (6). The flexible platen is of a scalable structure. Therefore, when the flexible platen stretches or expands to have a larger volume, the flexible platen applies a downward pressure to the upper platen assembly (9) connected to the flexible platen, so that the upper platen assembly (9) moves downwards slowly. After the upper platen assembly (9) and a lower platen assembly (7) are both adhered to objects to be bonded tightly, the flexible platen continues applying the downward pressure to the upper platen assembly (9). In this way, the upper platen assembly (9) can apply a pressure to the objects to be bonded evenly. In addition, the flexible platen has the flexibility, and is relatively slow in stretching or volume expansion. Therefore, it is ensured that the upper platen assembly (9) applies a pressure slowly and evenly.